

USSN: 09/491,302

Docket No.: 55271US002

first conductive layer mounted adjacent to the second side of the conductive trace layer;

a plurality of interconnect regions extending through the first conductive layer and the dielectric material layer of the capacitor; and

an interconnect member connected between each of the conductive layers of the capacitor and a corresponding set of the interconnect pads, the first conductive layer of the capacitor being electrically connected to a first set of the interconnect pads and the second conductive layer of the capacitor being electrically connected to a second set of the interconnect pads, the interconnect members corresponding to the second set of interconnect pads extending through one of the interconnect regions.

Cont.
A1

A2 Claim 19 (Amended). The electronic package of claim 18 wherein the dielectric substrate has an aperture extending therethrough adjacent to each solderball pad.

A version marked up to show changes made to the claim(s) relative to the previous version of the claim(s) is attached.